# Am1702A

256 x 8-Bit Programmable ROM

## DISTINCTIVE CHARACTERISTICS

- Access times down to 550 nanoseconds
- 100% tested for programmability
- Inputs and outputs TTL compatible

- Three-state output wired-OR capability
- Typical programming time of less than 2 minutes/device
- Clocked VGG mode for lower power dissipation

#### **GENERAL DESCRIPTION**

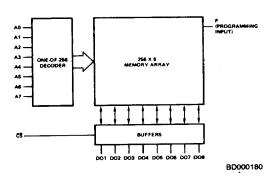
The Am1702A is a 2048-bit electrically programmable ultraviolet light erasable Read Only Memory. It is organized as 256 by 8 bits. It is packaged in a 24 pin dual in-line hermetic cerdip package with a foggy lid.

The transparent lid allows the user to erase any previously stored bit pattern by exposing the die to an ultraviolet (UV)

light source. Initially, and after each erasure, all 2048 bits are in the zero state (output low). The data is selectively written into specified address locations by writing in ones.

A low power version, the Am1702AL, is available which permits the VGG input to be clocked for lower average power dissipation.

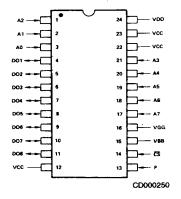
### **BLOCK DIAGRAM**



## PRODUCT SELECTOR GUIDE

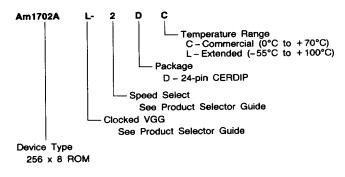
	Clocked				
1000	650	550	VGG		
Am1702A	Am1702A-2	Am1702A-1	No		
Am1702AL	Am1702AL-2	Am1702AL-1	Yes		
Am9702AHDL	Am9702A-2HDL	Am9702A-1HDL	No		
Am90702ALHDL	Am9702AL-2HDL	Am9702AL-1HDL	Yes		

## CONNECTION DIAGRAM Top View



Note: Pin 1 is marked for orientation

## ORDERING INFORMATION



Valid Combinations					
		Clocked VGG			
Am1702A Am1702A-2 Am1702A-1	DC, DC, DC	NO			
Am1702AL Am1702AL-2 Am1702AL-1	DL, DL, DL	YES			
Am9702AHDL Am9702A-2HDL Am9702AL-1HDL	DL, DL, DL	NO			
Am90702AL-HDL Am90702AL-2HDL Am90702AL-1HDL	DL	YES			

## PROGRAMMING THE Am1702A

Each storage node in the Am1702A consists of an MOS transistor whose gate is not connected to any circuit element. The transistors are all normally off, making all outputs LOW in an unprogrammed device. A bit is programmed to a HIGH by applying a large negative voltage to the MOS transistor; electrons tunnel through the gate insulation onto the gate itself. When the programming voltage is removed, a charge is left on the gate which holds the transistor on. Since the gate is completely isolated, there is no path by which the charge can escape, except for random high energy electrons which might retunnel through the gate insulation. Under ordinary conditions retunneling is not significant. The application of high energy to the chip through X-rays or UV light (via the quartz window) raises energy levels so that the charge can escape from the gate region, erasing the program and restoring the device to all LOW.

In order to program a specified byte, all 8 address lines must be in the binary complement of the address desired when pulsed VDD and VGG move to their negative level. The complemented address must be stable for at least tACW before VDD and VGG make their negative transitions. The voltage swing of the address lines during programming is between  $-47V \pm 1V$  and 0V. The addresses must then make a transition to the true state at least tATW before the program pulse is applied. For good data retention, the addresses should be programmed in sequence from 0 to 255, a minimum of 32 times. DO1 through DO8 are used as the data inputs to program the desired pattern. A low level at the data input (-47V  $\pm$ 1V) will program the selected bit to 1 and a high level (0V) will program it to a 0. All 8 bits addressed are programmed simultaneously.

Programming Boards are available for the Data I/O automatic programmer (part number 1010/1011), for the Spectrum Dynamics programmer (part number 434-549), and for the Pro-Log programmer (part number PM9001).

#### FRASING THE Am1702A

The Am1702A may be erased (restored to all LOW's) by exposing the die to ultraviolet light from a high intensity source. The recommended dosage is 6 W-sec/cm2 at a wavelength of 2537 Å. The Ultraviolet Products, Inc., models UVS-54 or S-52 can erase the Am1702A in about 15 minutes, with the devices held one inch from the lamp. (Caution should be used when Am1702A's are inspected under fluorescent lamps after being programmed, as some fluorescent lamps may emit sufficient UV to erase or "soften" the PROM.)

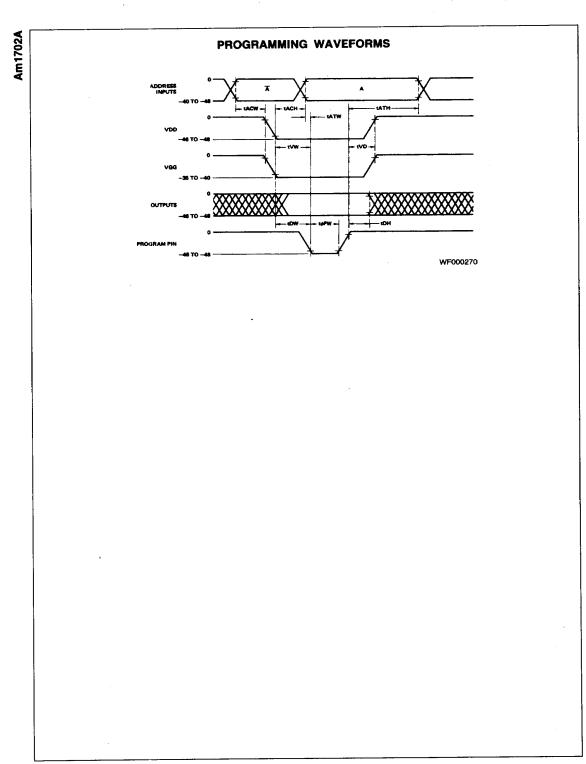
#### CAUTION

Ultraviolet radiation is invisible and can damage human eyes. Precautions should be taken to avoid exposure to direct or reflected ultraviolet radiation. It will often be convenient to fully enclose the ultraviolet source and the EROMs being erased to prevent accidental exposure.

Ultraviolet lamps can also ionize oxygen and create ozone which is harmful to humans. Erasing should be carried out in a well ventilated area in order to minimize the concentration of ozone.

## **PROGRAMMING**

PROGRA		Test Conditions	Min	Тур	Max	Units
Symbol	Parameter				10	mA
ILITP	Input Current, Address and Data	V <sub>I</sub> = -48V			10	mA
Li2P	Input Current, Program and VGG Inputs	V <sub>I</sub> = -48V		0.05		· mA
IBB	V <sub>BB</sub> Current			200	Note 8	mA
IDOP	IDD Current During Programming Pulse	V <sub>DD</sub> = V <sub>Prog</sub> = -48V, V <sub>GG</sub> = -35V			0.3	Volts
ViHP	Input HIGH Voltage				-48	Volts
V <sub>IL1P</sub>	Voltage Applied to Output to Program a HIGH		-46	<del> </del>	-48	Volts
VILZP	Input LOW Level on Address Inputs		-46		-48	Votts
V <sub>IL3P</sub>	Voltage Applied to V <sub>DD</sub> and Program Inputs		-35	<b>├</b>	-40	Volt
V <sub>IL4P</sub>	Voltage Applied to VGG Input	101/		+-	3.0	ms
t <sub>o</sub> pw	Programming Pulse Width	V <sub>GG</sub> = -35V, V <sub>DD</sub> = V <sub>Prog</sub> = -48V	25	-	+	μs
tDW.	Data Set-up Time		10	+	+	μѕ
ton-	Data Hold Time	·	100	+	+	μs
tvw	V <sub>GG</sub> and V <sub>DD</sub> Set-up Time		10	+	100	μs
tvp	V <sub>GG</sub> and V <sub>DD</sub> Hold Time		25	+		μs
tacw	Address Set-up Time (Complement)		25	+		μз
tach	Address Hold Time (Complement)		10	+	+	μs
tATW	Address Set-up Time (True)		10	+	+	μ
tATH	Address Hold Time (True)		<del></del> -	+	20	%
AIH	Duty Cycle					



#### **ABSOLUTE MAXIMUM RATINGS**

Storage Temperature	65°C to +150°C
Ambient Temperature with	12 2 10 1 100 0
Power Applied	55°C to +85°C
Input and Supply Voltages	
Operating	Vcc-20V to Vcc+0.5V
Programming	
Power Dissipation	1.0W

The products described by this specification include internal circuitry designed to protect input devices from damaging accumulations of static charge. It is suggested nevertheless, that conventional precautions be observed during storage, handling and use in order to avoid exposure to excessive voltages.

#### **OPERATING RANGES**

Temperature
1702 Devices0°C to +70°C
9702 Devices55°C to +85°C
Supply Voltages
V <sub>CC</sub> , V <sub>BB</sub> +4.75V to +5.25V
V <sub>DD</sub> , V <sub>GG</sub> 8.55V to +9.45V
Operating ranges define those limits over which the functional- ity of the device is guaranteed.

## DC CHARACTERISTICS over operating range unless otherwise specified

			Am1702A Am9702A			Am1702AL Am9702AL				
Symbol		_	Test Conditions		Тур	Max	Min	Тур	Max	Unite
ICF1	Output Clamp Current		°C, V <sub>O</sub> = -1.0V		8	14	<del>                                     </del>	5.5	8	mA
I <sub>CF2</sub>	Output Clamp Current	TA = 2	5°C, V <sub>O</sub> = -1.0V			13		5	7	mA
IDD0		V <sub>GG</sub> = V <sub>CC</sub> , I <sub>OL</sub> = 0mA V <sub>CS</sub> = V <sub>CC</sub> - 2.0, T <sub>A</sub> = 25°C						7	10	mA
PDD1	V <sub>DD</sub> Current (Note 4)	IOL = 0	mA, VCS = V <sub>CC</sub> -2.0,T <sub>A</sub> = 25°C		35	50		35	50	mA
IDD2	]	IOL = 0	mA,Vcs = 0, T <sub>A</sub> = 25°C		32	46		32	46	mA
I <sub>DD3</sub>		IOL = 0mA, VCS = VCC-2.0,TA = 0°C			38	60		38	60	mA
lgg	V <sub>GG</sub> Current	1			<u> </u>	1.0			1.0	μА
ILI	Input Leakage Current	VI - 0V			<del></del>	1.0			1.0	μA
Į <sub>L</sub> O	Output Leakage Current	CS = V	CC -2.0, VO = 0V			1.0			1.0	μA
Юн	Output Source Current	Vo = 0	v	-2.0	-		-2.0		1.0	mA
loL	Output Sink Current	Vo = 0.	45V	1.6	4		2.0			mA
VIH	Input HIGH Level			V <sub>CC</sub> -2.0		V <sub>CC</sub> + 0.3	V <sub>CC</sub>		V <sub>CC</sub>	Volts
VIL	Input LOW Level			-1.0	- 1	0.65	-1.0		0.65	Volts
VOH	Output HIGH Level	IOH = -	200μΑ	3.5	4.5		3.5	4.5	0.03	Volts
VOL	Output LOW Level	1.	1.6mA		-3.0	0.45				
-01	Cuput LOW Level	IOL 2.0mA							0.4	Volts
Cı	Input Capacitance	] —						8	15	
Co	Output Capacitance	TA = 25°C All unused pins are at V <sub>CC</sub>			-		$\dashv$	10	15	ρF
CvGG	V <sub>GG</sub> Capacitance					-		·••	30	ρF

#### Notes:

- During read operations VGG may be clocked high to reduce power consumption. This involves swinging VGG up to VCC. See "Clocked VGG Operation". This mode is possible only with the Am1702AL.
- 2. During Read operations:

Pins 12, 13, 15, 22,  $23 = +5.0V \pm 5\%$ 

Pins 16,  $24 = -9.0V \pm 5\%$ 

**During Program operations:** 

tA = 25°C

Pins 12, 22, 23 = 0V

Pins 13, 24 are pulsed low from 0V to  $-47V \pm 1V$ 

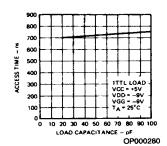
Pin  $15 = +12.0V \pm 10\%$ 

Pin 16 is pulsed low from 0V to -37.5V ±2.5V

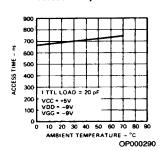
- Typical values are for T<sub>A</sub> = 25°C, nominal supply voltages and nominal processing parameters.
- 4. IDD may be reduced by pulsing the VGG supply between VCC and –9V. VDD current will be directly proportional to the VGG duty cycle. The data outputs will be unaffected by address or chip select changes while VGG is at VCC. For this option specify AM1702AL.
- 5. VIL = 0V, VIH = 4.0V, tr = tf  $\leq$  50ns, Load = 1 TTL gate.
- The output will remain valid for tOHC after the VGG pin is raised to VCC, even if address change occurs.
- These parameters are guaranteed by design and are not 100% tested.
- 8. Do not allow IDD to exceed 300mA for more than  $100\mu\text{sec}$ .

## DC OPERATING CHARACTERISTICS

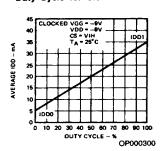
Access Time
Versus Load Capacitance



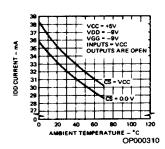
Access Time Versus Temperature



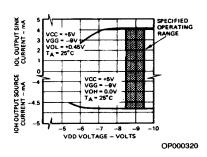
Average Current Versus
Duty Cycle for Clocked VGG



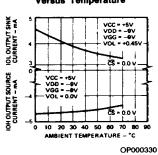
IDD Current Versus Temperature



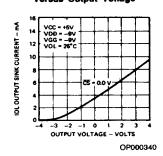
Output Current Versus VDD Supply Voltage



Output Current Versus Temperature



Output Sink Current Versus Output Voltage



SWITCHING CHARACTERISTICS over operating range unless otherwise specified									
		Description	Am17 Am9	Am1702A-1 Am1702AL-1 Am9702A-1 Am9702AL-1		Am 1702A-2 Am 1702AL-2 Am 9702A-2 Am 9702AL-2		Am1702A Am1702AL Am9702A Am9702AL	
No.	lo. Symbol		Min	Max	Min	Max	Min	Max	Unit
1	tACC	Address to Output Access Time		550		650		1000	ns
2	tco	Output Delay from CS		450		350		900	ns
3	tës	Chip Select Delay		100		300		100	ns
4	tovag	Set-up Time, V <sub>GG</sub>	0.3		0.3		0.4		μs
5	ton	Output Deselect		300		300		300	ns
6	tон	Previous Read Data Valid		100		100		100	ns

100 5.0

1.8

5.0

1.6

5.0

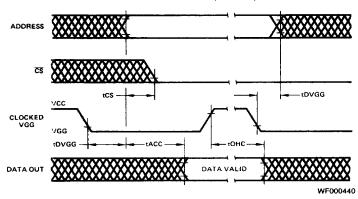
1.0

μs

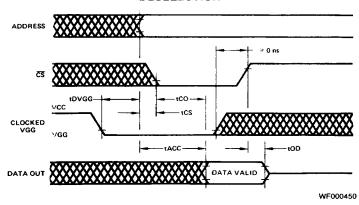
MHz

## **SWITCHING WAVEFORMS**

### **READ OPERATION** (Note 2)



#### **DESELECTION**



Note 1: CLOCKED VGG OPERATION

tонс freq.

Repetition Rate

Data Out Valid from VGG (Note 6)

The VGG input may be clocked between +5V (VCC) and -9V to save power. To read the data, the chip select (CS) must be low ( ≤ VIL) and the VGG level must be lowered to -9V at least tDVGG prior to the address selection. Once the data has appeared at the output and the access time has elapsed, VGG

may be raised to +5V. The data output will remain stable for tOHC. To deselect the chip, CS is raised to ≥ VIH, and the output will go the high impedance state after tOD. The chip will be deselected when CS is raised to VIH whether the VGG is at +5V or at -9V.